

An 8-ch, 20-V Output CMOS Switching Driver with 3.3-V Power Supply for Integrated MEMS Devices Controlling

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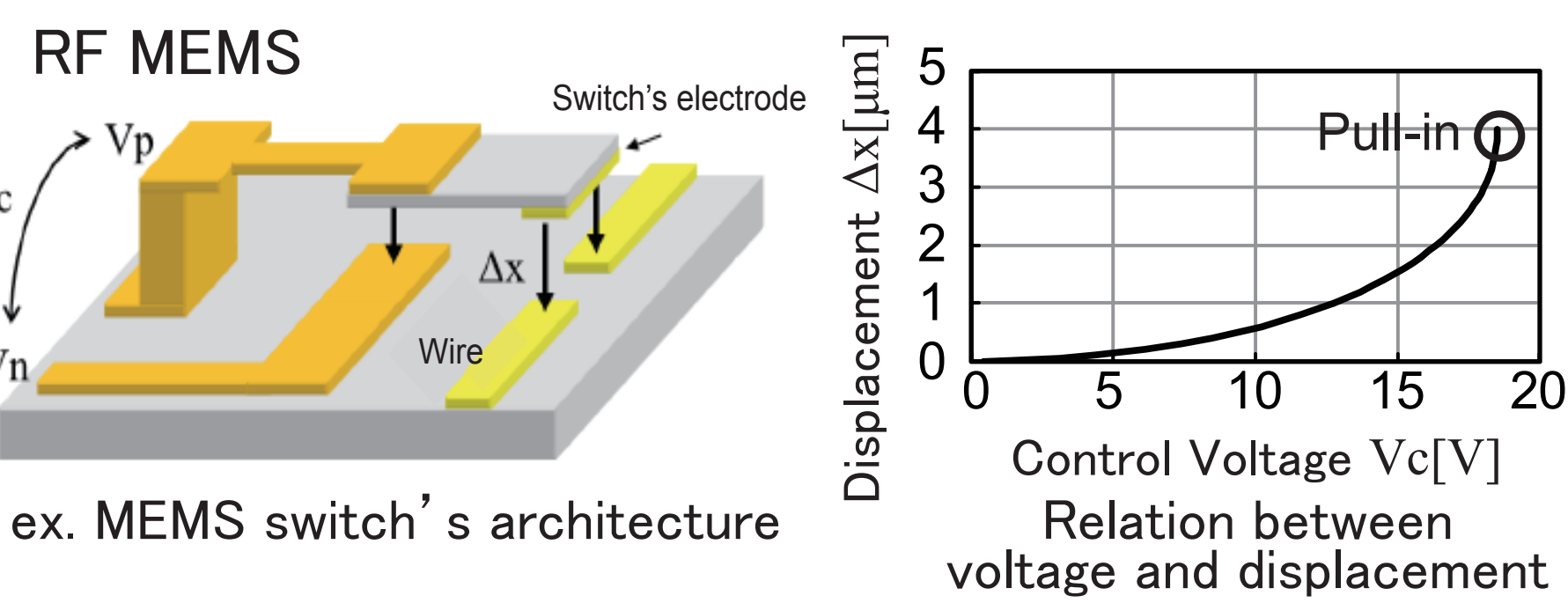
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1. Background

Purpose

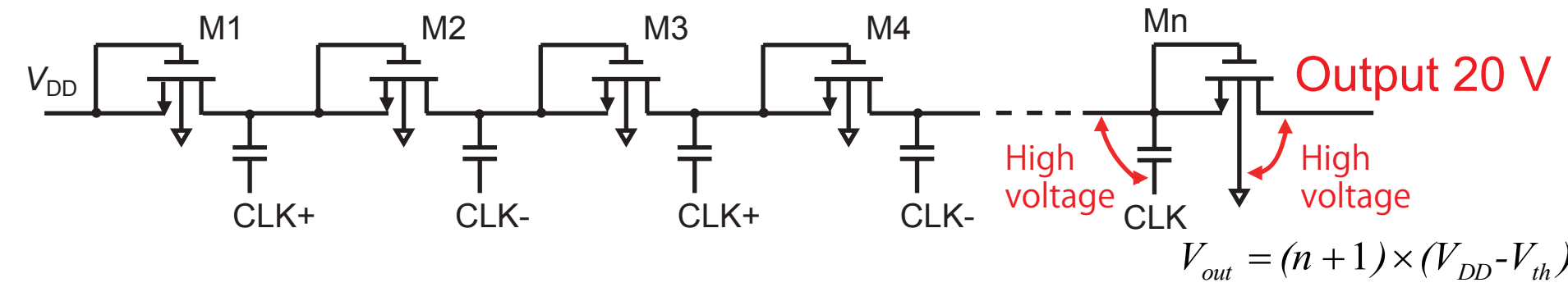
To implement MEMS for RF devices integrating MEMS & CMOS technology



- Pros
- Low loss
 - Small & High performance
- Cons
- Required high voltage around 20 V
 - Integration of CMOS Technology

Subject

- Conventional: Dickson type Charge pump

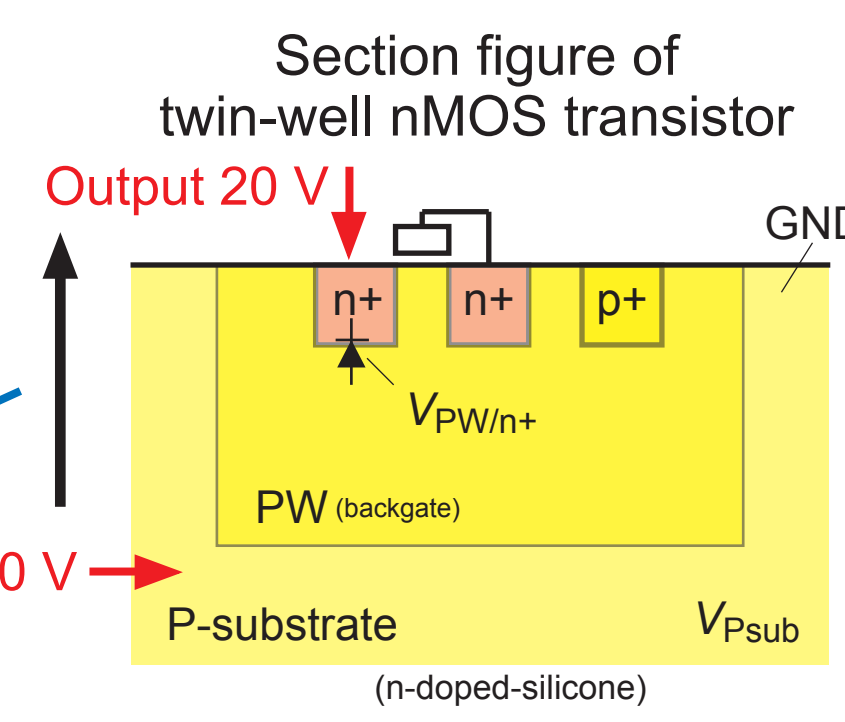


Breakdown voltage (180-nm CMOS)

- MIM capacitor: 5 V
- Transistor
- PW/n+: 11 V

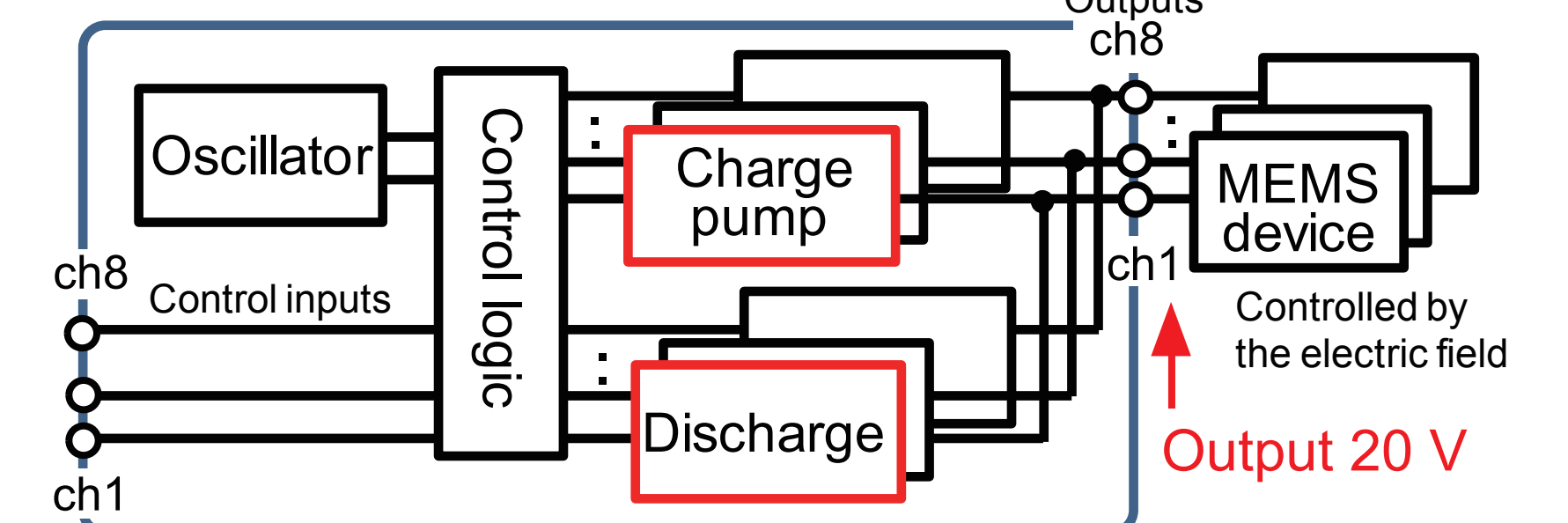
Voltage PN junction $20 \text{ V} > 11 \text{ V}$

exceeding transistor's breakdown voltage



Goal

An 8-ch, 20-V Output CMOS Switching driver using standard 0.18- μm CMOS Technology

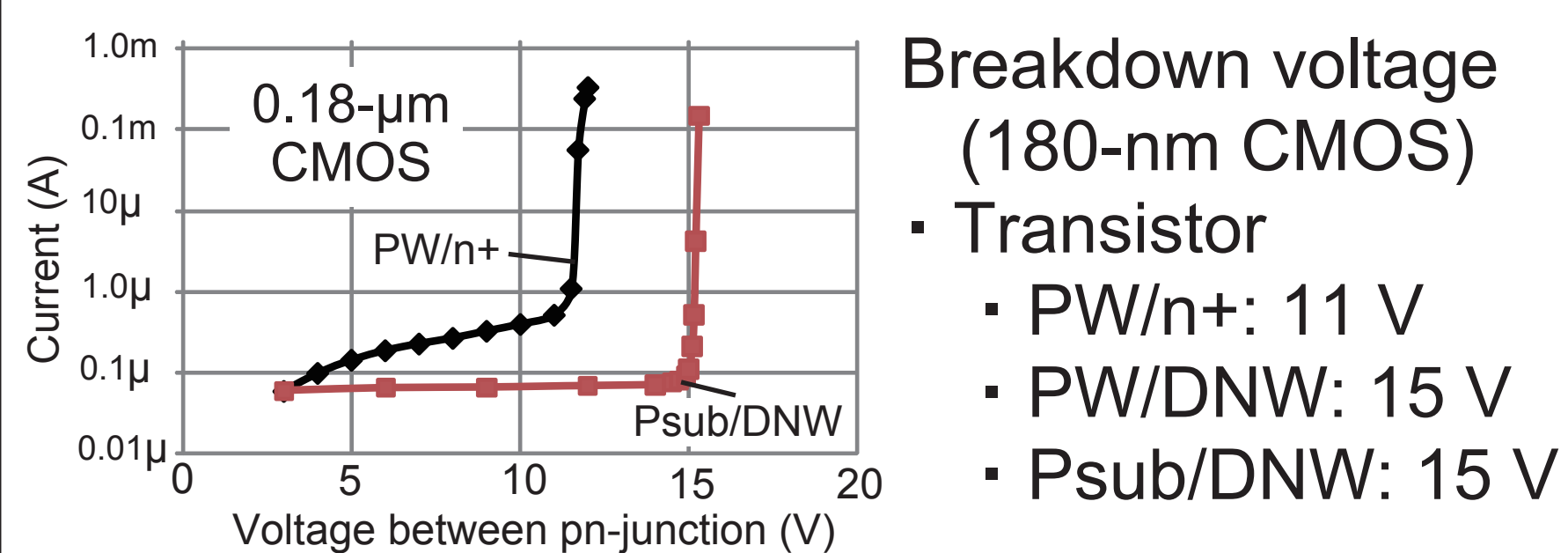
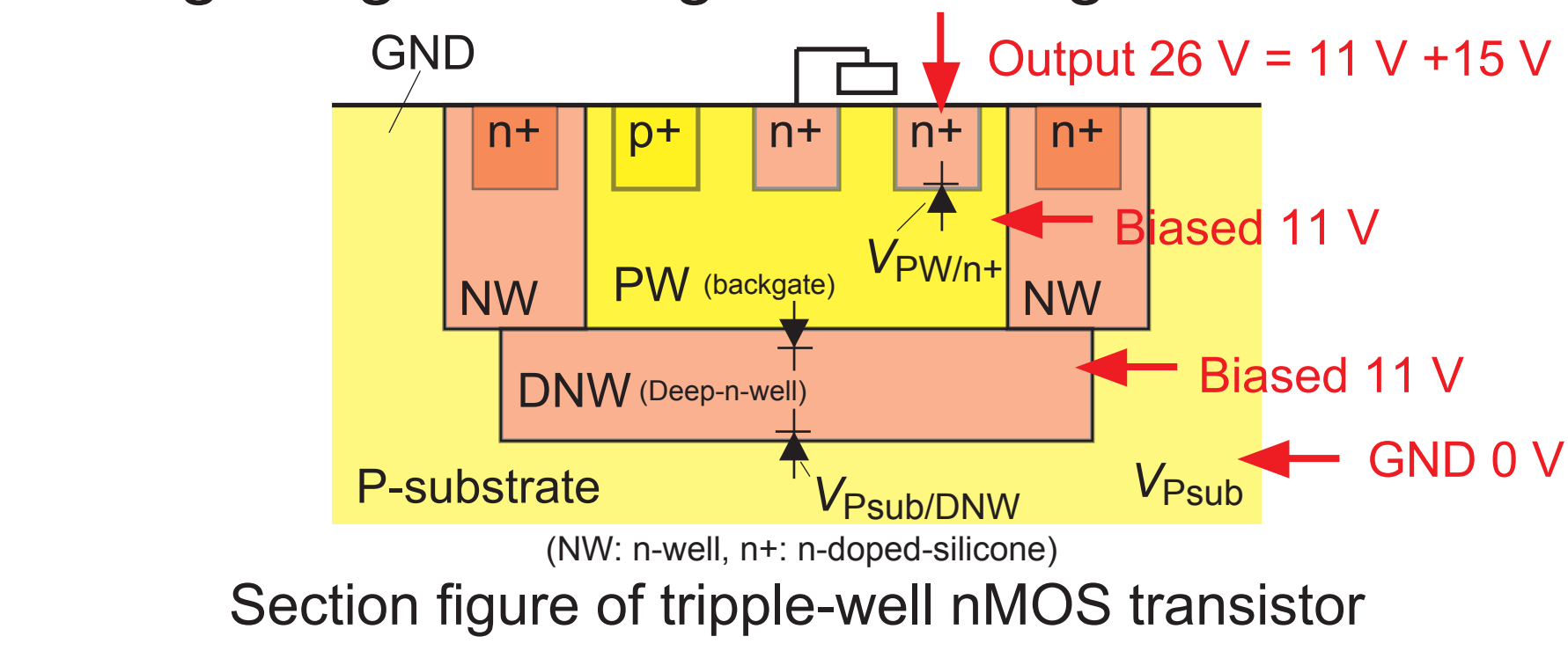


- 8-sets of charge pump, discharge circuits, oscillator and control logic circuit.
- Charge pump : Low \rightarrow High (20 V).
- Discharge circuit : High (20 V) \rightarrow Low.

2. Proposed CMOS Switching Driver

Tripple well transistor

to get higher voltage exceeding breakdown



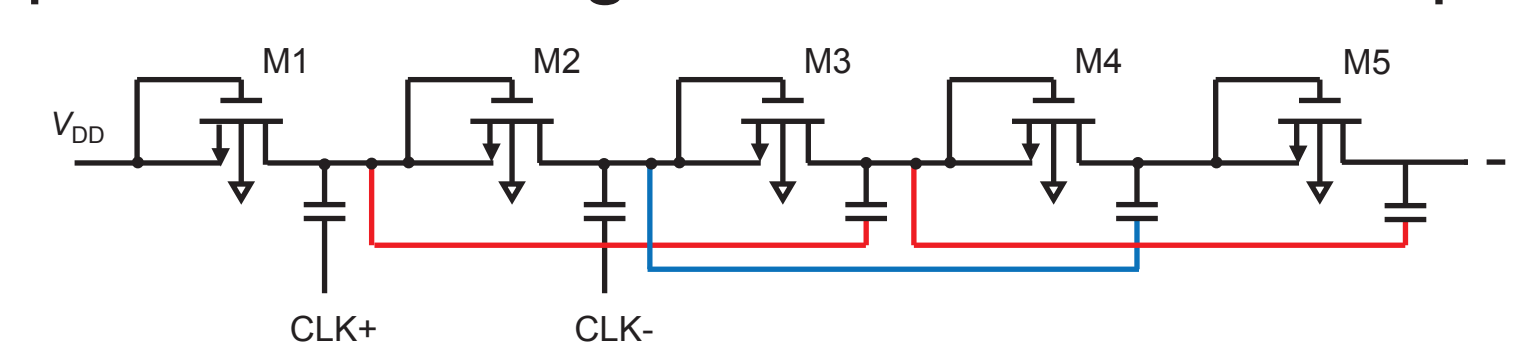
- Transistor
- PW/n+: 11 V
- PW/DNW: 15 V
- Psub/DNW: 15 V

Improved maximum output voltage

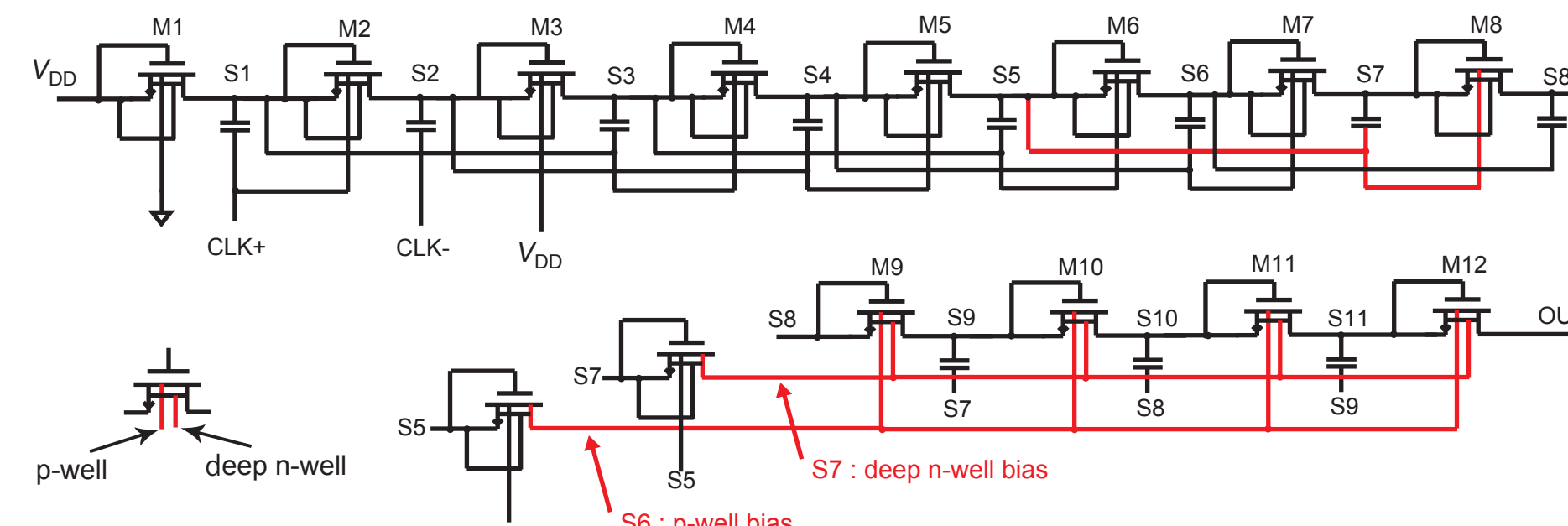
$$V_D < V_{PW/n+} + V_{Psub/DNW} = 11 \text{ V} + 15 \text{ V} = 26 \text{ V}$$

Charge pump

- Proposed: Clock signal distribution technique



- Proposed: Charge pump using tripple-well transistor



For capacitor's break down voltage

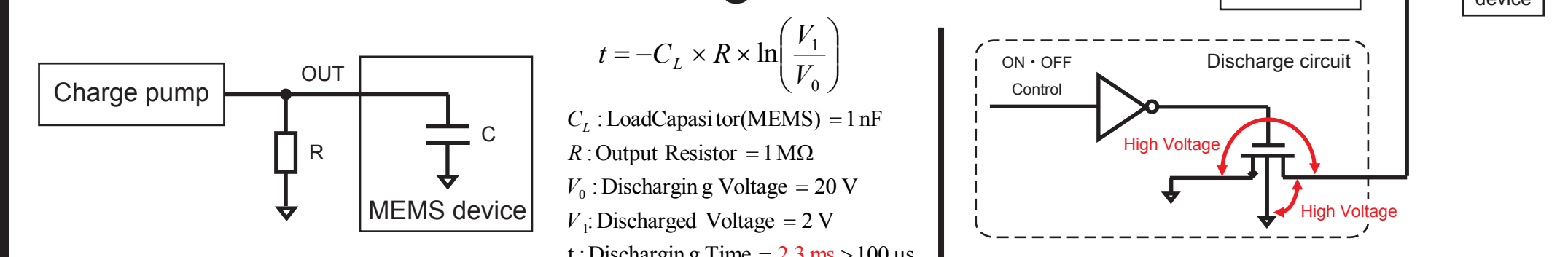
Later stages use previous stage's signal.

For transistor's breakdown voltage

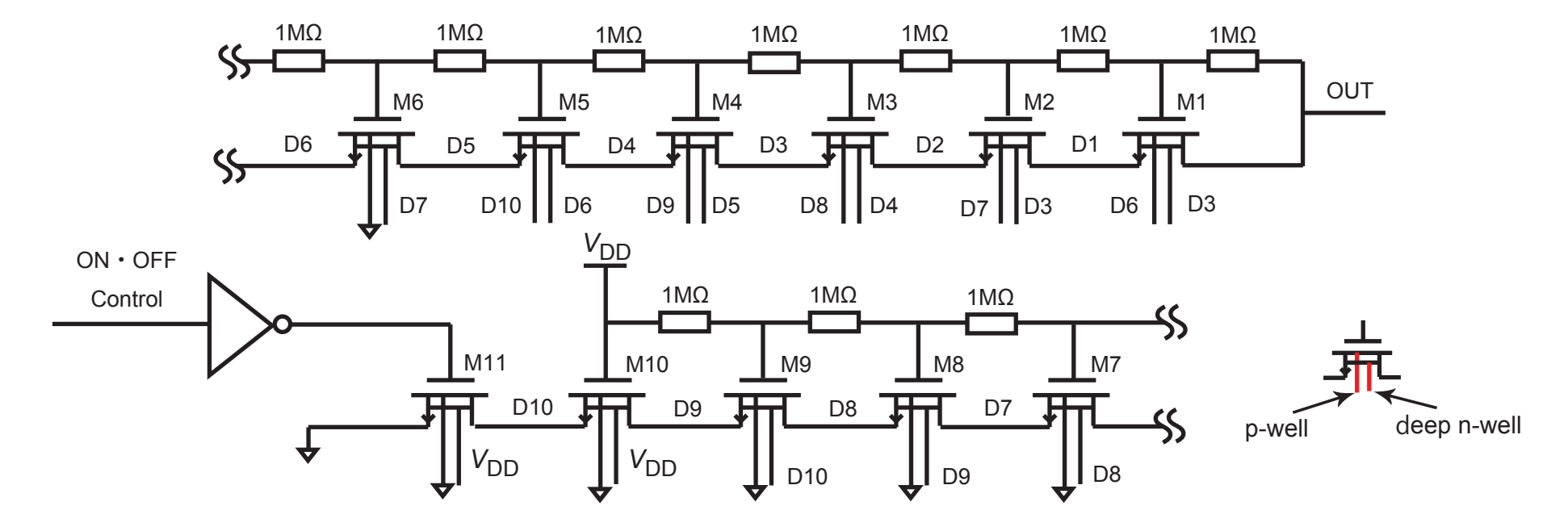
PW, DNW are biased by previous voltage.

Discharge circuit

- Conventional: Discharge circuit



- Proposed: cascaded discharge circuit



For transistor's D-S breakdown voltage

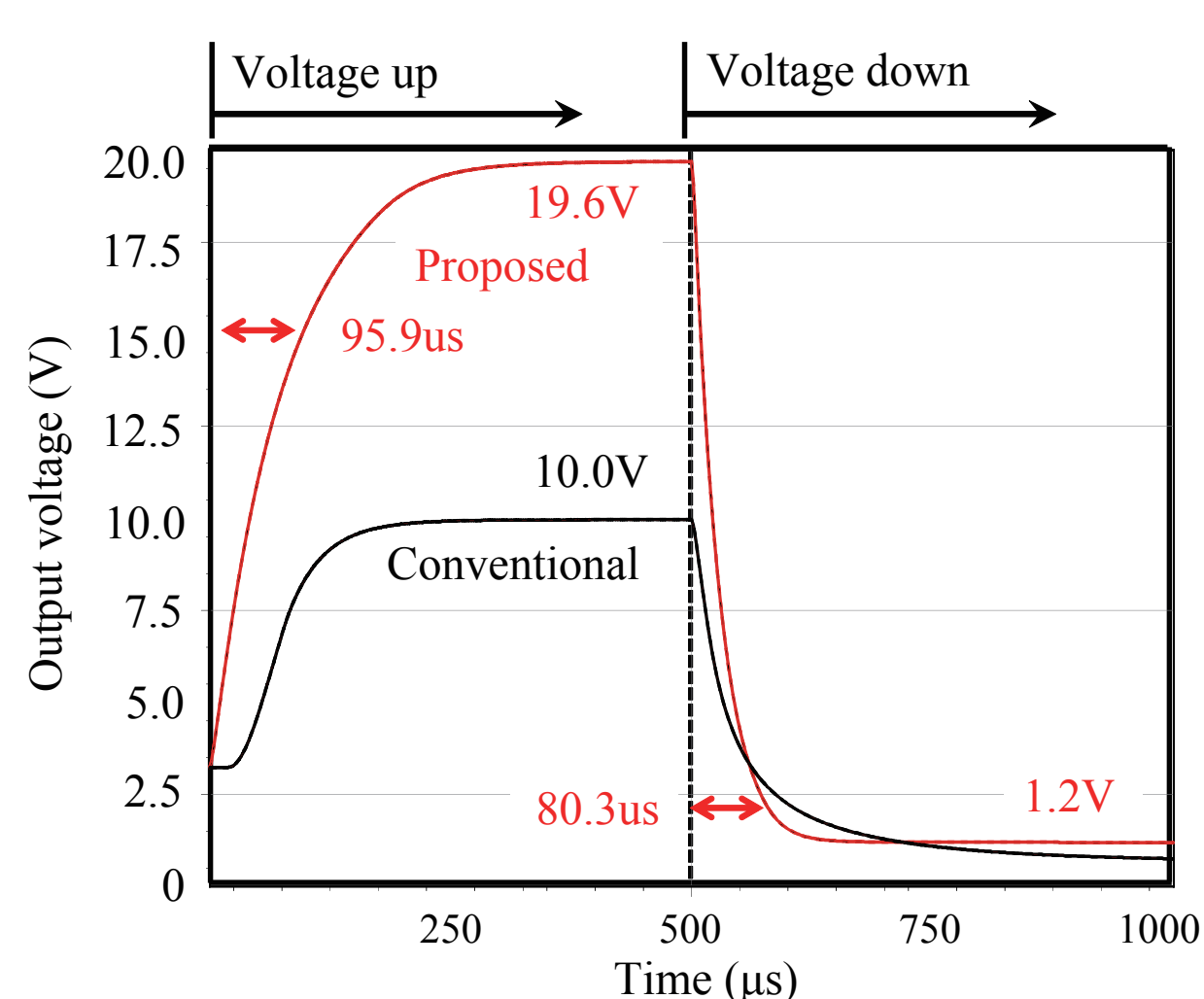
10-stages transistor's are cascaded.

For leakage of charging current

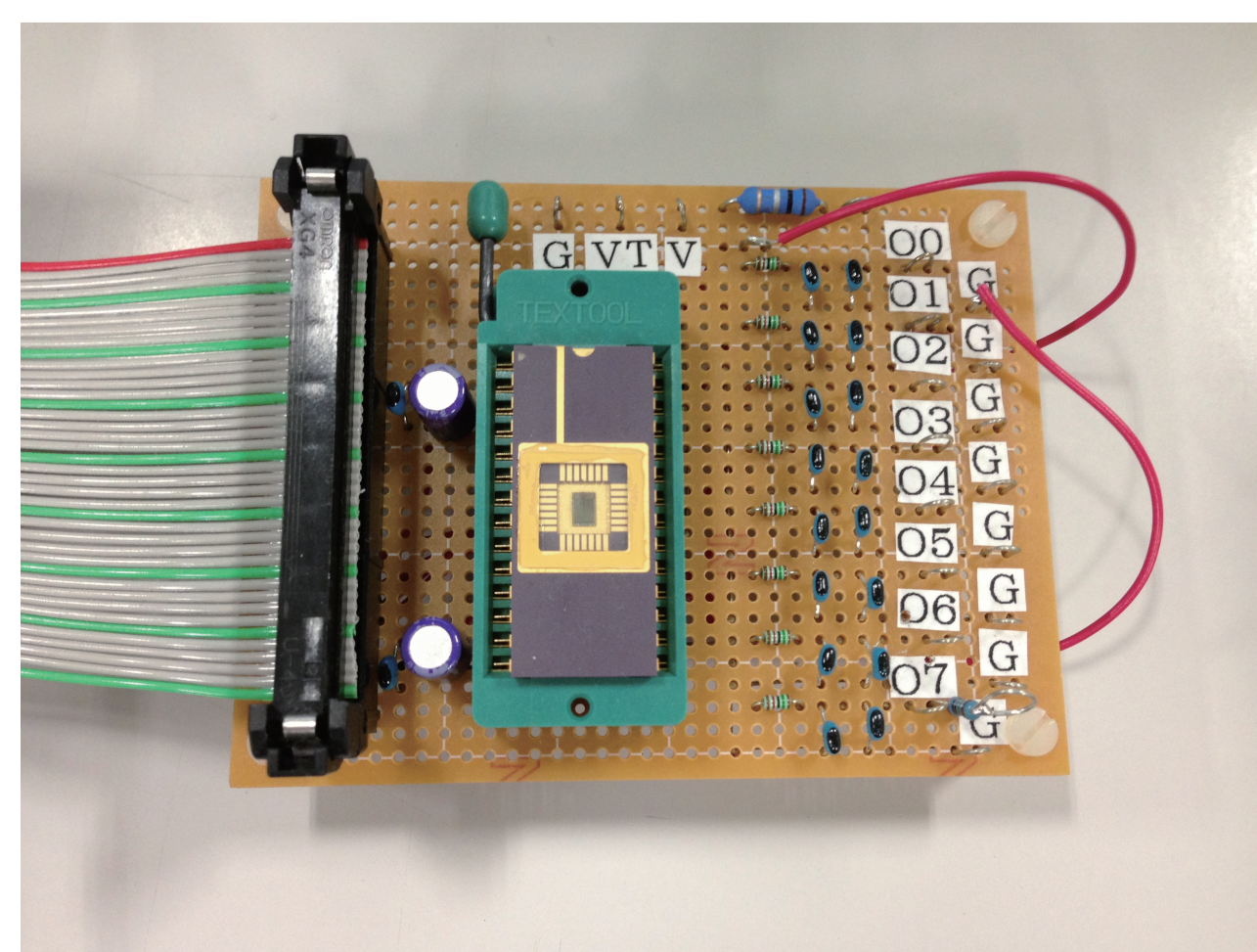
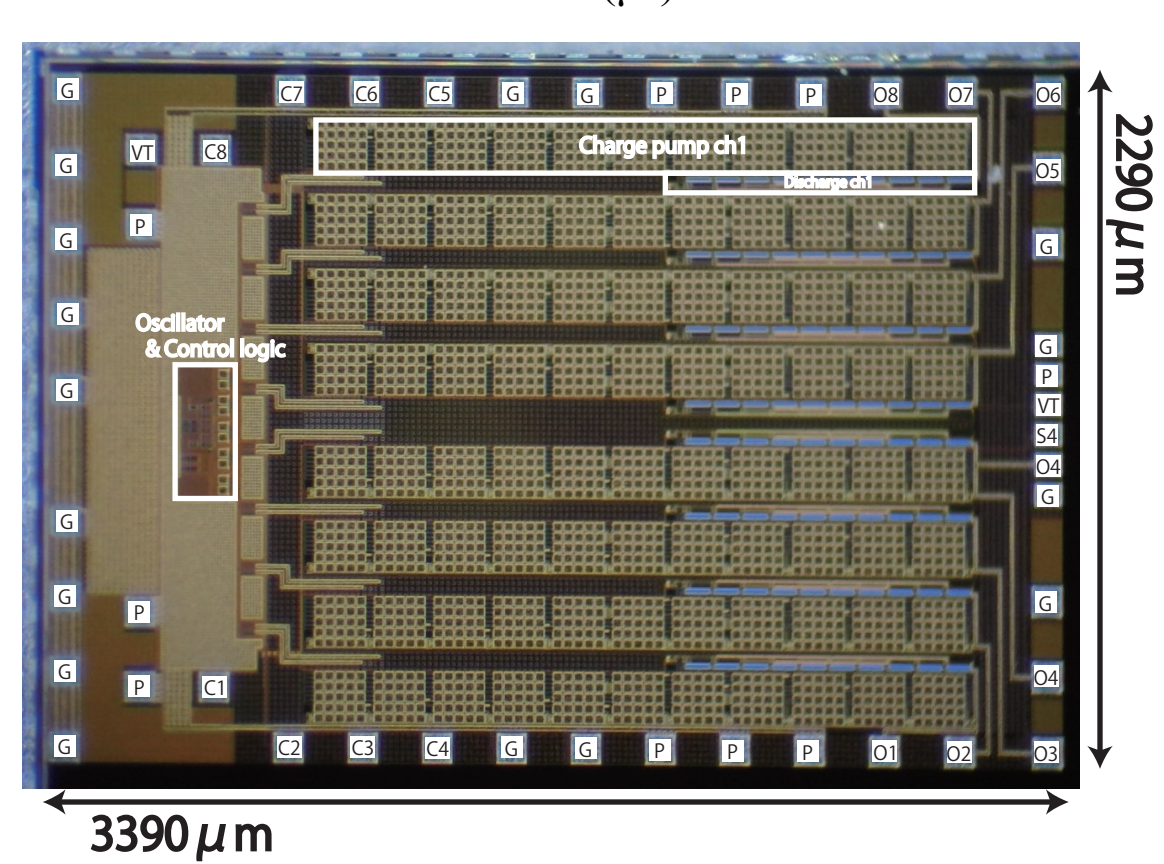
High resistor are used (Charge: 10M Ω , Discharge: 42k Ω)

3. Measured Results

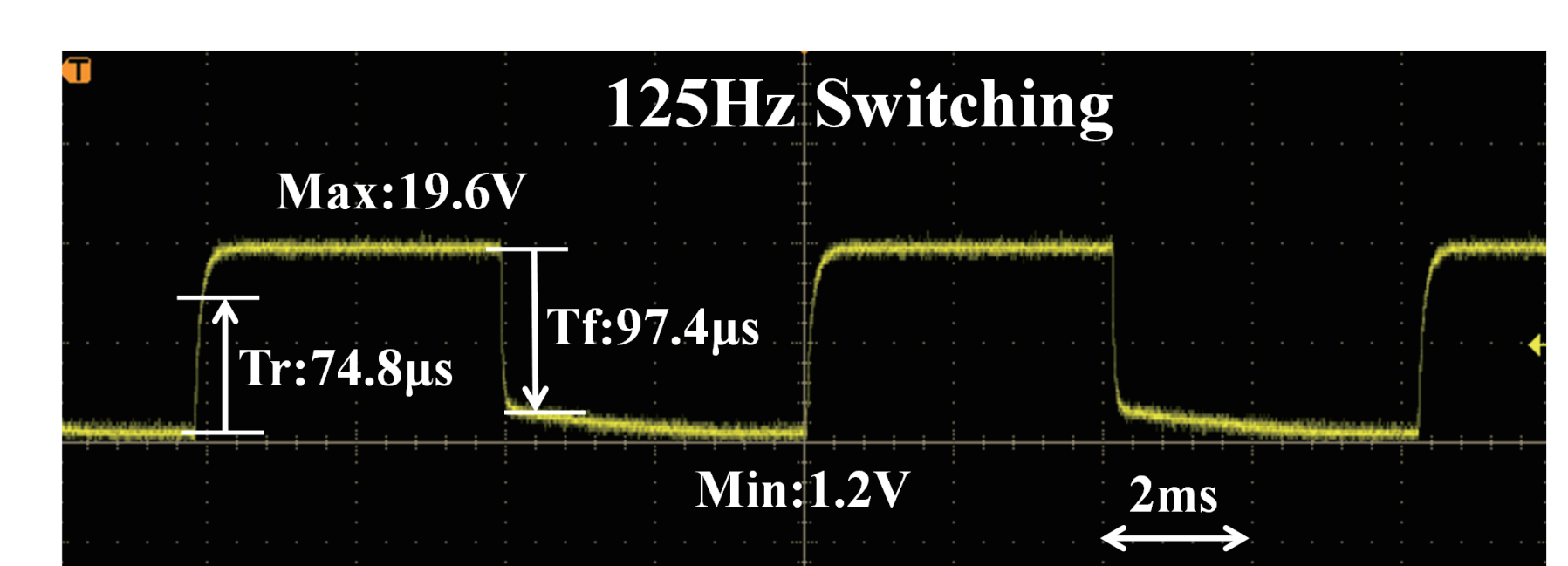
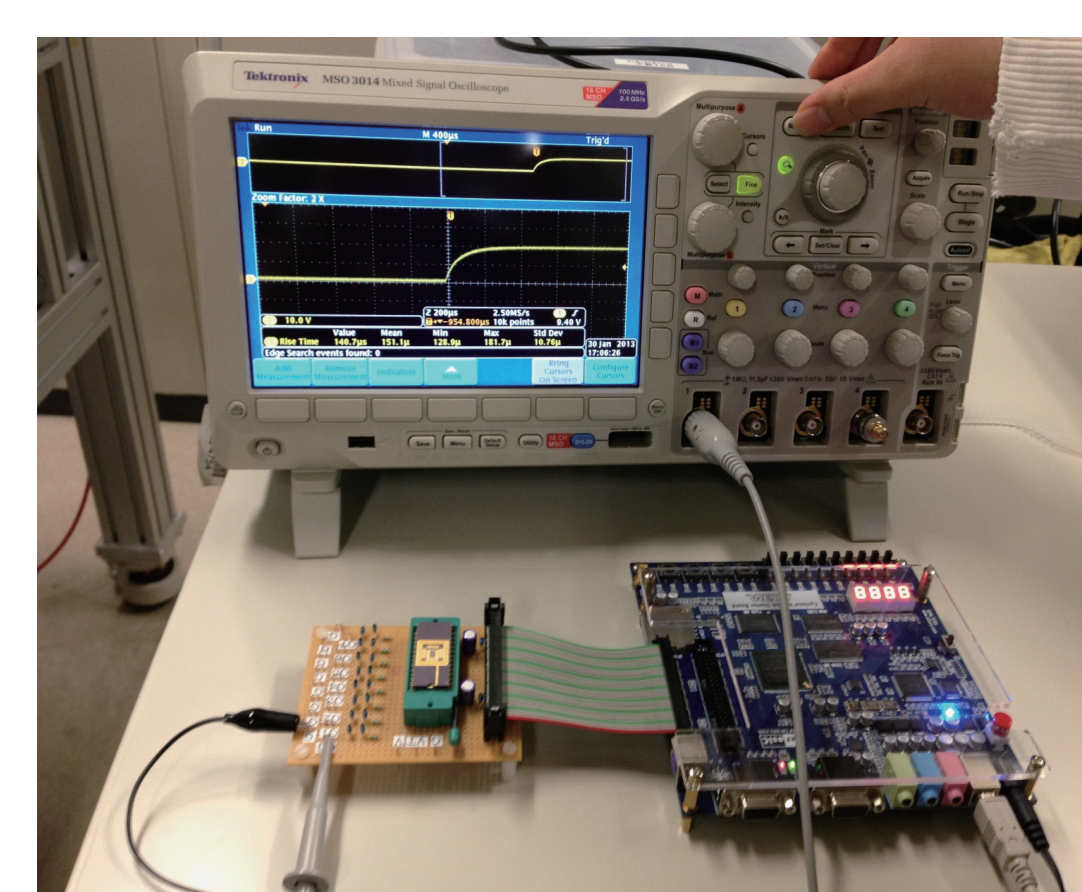
Simulation & Fabricated Chip



- Output voltage exceeded Tr's breakdown with 1.3-nF capacitive load
- Quick charge and discharge < 100 μs
- Fabricated by 0.18- μm CMOS process



Measurement



Confirmed 8-ch output independently
Performance summary

Item	Goal	Measured Result
Output voltage (High)	20 V	19.6 V
Output voltage (Low)	2 V	1.2 V
Output channel	8 ch	8 ch
Load	1 nF	1.3 nF
Rise and fall Time	tr/TF < 100 μs	tr: 74.8 μs (15 V) tf: 97.4 μs (3.3 V)
Power supply voltage	3.3 V	3.3 V
Power dissipation		85.3 mW (1 ch) 106 mW (8 ch)
Chip size	< 2400*3500 μm^2	2290*3390 μm^2
CMOS process	0.18 μm	0.18 μm

4. Conclusion

An 8-ch, 20-V output CMOS switching driver with 3.3-V power supply was designed and fabricated.

a) Confirmed 20-V output voltage exceeding 11-V transistor's breakdown voltage.

b) Tripple-well-structured n-MOS transistors were implemented in charge pump and discharging circuit.

c) Invented optimal transistor-well-biasing techniques to exceed transistor's breakdown voltage.